



## **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub>	I <sub>D</sub> T <sub>A</sub> = +25°C	
-100V	350mΩ @ V <sub>GS</sub> = -10V	-1.6A	
-1000	450mΩ @ V <sub>GS</sub> = -6V	-1.4A	

## Description

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## Applications

- Motor Control
- DC-DC Converters
- Power Management Functions
- Uninterrupted Power Supply

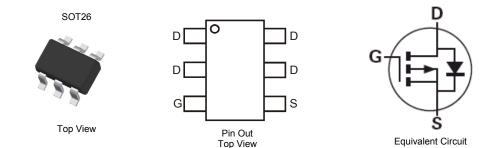
#### **100V P-CHANNEL ENHANCEMENT MODE MOSFET**

#### **Features and Benefits**

- Fast Switching Speed
- Low gate drive
- Low input capacitance
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

### **Mechanical Data**

- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See diagram below
- Terminals: Finish Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.018 grams (approximate)



## Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
ZXMP10A17E6TA	Standard	SOT26	3,000/Tape & Reel

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

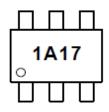
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html

## **Marking Information**

Notes:



1A17 = Product Type Marking Code



### Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage		V <sub>DSS</sub>	-100	V	
Gate-Source Voltage			V <sub>GS</sub>	±20	V
		(Note 6)		-1.6	
Continuous Drain Current	V <sub>GS</sub> = 10V	T <sub>A</sub> = +70°C (Note 6)	ID	-1.3	А
		(Note 5)		-1.3	
Pulsed Drain Current	V <sub>GS</sub> = 10V	(Note 7)	I <sub>DM</sub>	-7.7	А
Continuous Source Current (Body diode)		(Note 6)	I <sub>S</sub>	-2.1	А
Pulsed Source Current (Body diode) (Note 7)		I <sub>SM</sub>	-7.7	А	

#### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power dissipation	(Note 5)	6	1.1 8.8	W	
Linear derating factor	(Note 6)		1.7 13.7	mW/°C	
Thermal Resistance, Junction to Ambient	(Note 5)	Deve	113	°C/W	
	(Note 6)		73	C/W	
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	٥°	

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

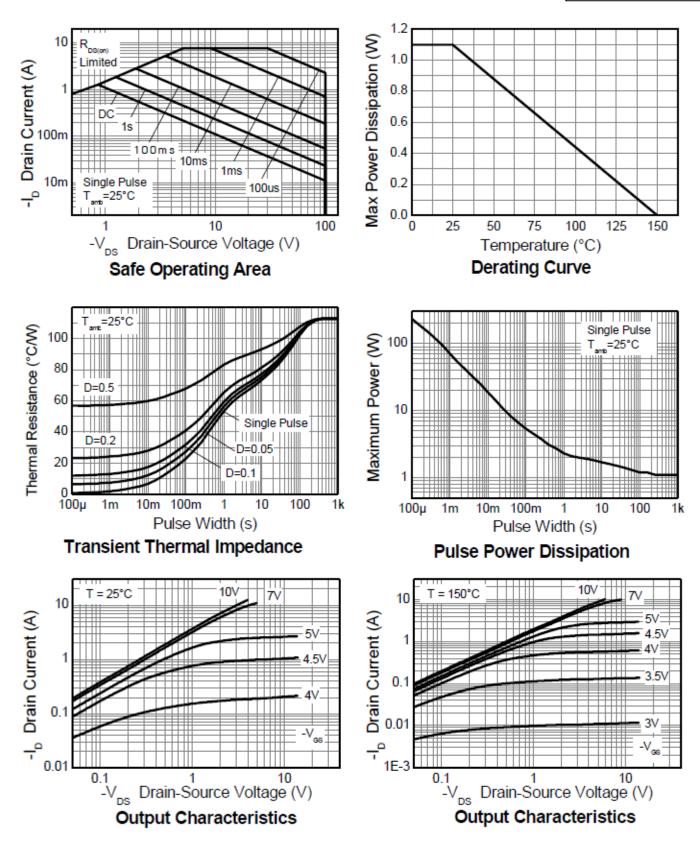
Characteristic	Symbol	Min	Тур	Max	Unit	Test	Condition
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	-100	_	_	V	I <sub>D</sub> = -250µA, V <sub>GS</sub> = 0V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	-0.5	μA	V <sub>DS</sub> = -100V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	IGSS		_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS			_	_	_		
Gate Threshold Voltage	V <sub>GS(th)</sub>	-2	_	-4	V	I <sub>D</sub> = -250μA, V	<sub>DS</sub> = V <sub>GS</sub>
Static Drain-Source On-Resistance (Note 8)				0.35	Ω	V <sub>GS</sub> = -10V, I <sub>D</sub>	= -1.4A
Static Drain-Source On-Resistance (Note 8)	R <sub>DS(ON)</sub>	_	_	0.45		$V_{GS}$ = -6V, $I_{D}$ =	-1.2A
Forward Transconductance (Notes 8 & 9)	<b>g</b> <sub>fs</sub>		2.8		S	V <sub>DS</sub> = -15V, I <sub>D</sub>	= -1.4A
Diode Forward Voltage (Note 8)	V <sub>SD</sub>	_	-0.85	-0.95	V	I <sub>S</sub> = -1.7A, V <sub>GS</sub> = 0V	
Reverse recovery time (Note 9)	trr		33	—	ns		
Reverse recovery charge (Note 9)	Qrr	_	48	_	nC		
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>	_	424	—	pF	V <sub>DS</sub> = -50V, V <sub>GS</sub> = 0V F = 1MHz	
Output Capacitance	C <sub>oss</sub>	_	36.6	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	29.8	_	pF		
Total Gate Charge (Note 10)	Qg	_	7.1	—	nC	V <sub>GS</sub> = -6V	
Total Gate Charge (Note 10)	Qg	_	10.7	—	nC		V <sub>DS</sub> = -50V
Gate-Source Charge (Note 10)	Qgs	_	1.7	—	nC	V <sub>GS</sub> = -10V I <sub>D</sub> = -1.4A	
Gate-Drain Charge (Note 10)	Q <sub>gd</sub>	_	3.8	_	nC		
Turn-On Delay Time (Note 10)	t <sub>D(on)</sub>		3	_	ns	V <sub>DD</sub> = -50V, V <sub>GS</sub> = -10V	
Turn-On Rise Time (Note 10)	tr	_	3.5	_	ns		
Turn-Off Delay Time (Note 10)	t <sub>D(off)</sub>	_	13.4	_	ns	I <sub>D</sub> = -1A, R <sub>G</sub> ≅	6Ω
Turn-Off Fall Time (Note 10)	t <sub>f</sub>	_	7.2	_	ns	1	

Notes: 5. For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition. 6. Same as note (5), except the device is measured at  $t \le 5$  sec.

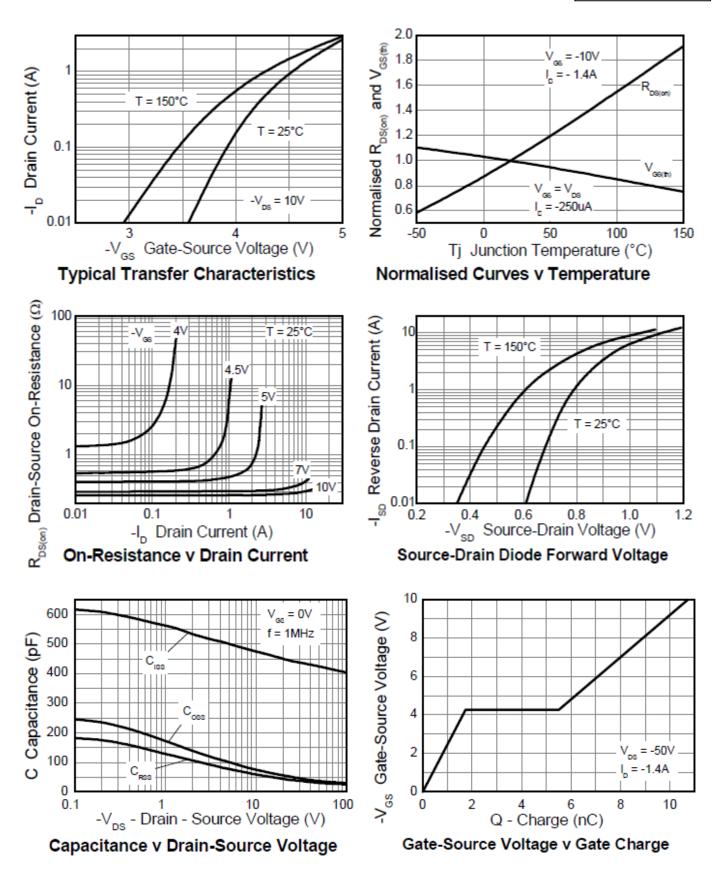
7. Same as note (5), except the device is pulsed with D = 0.05 and pulse width 10µs. The pulse current is limited by the maximum junction temperature. 8. Measured under pulsed conditions. Pulse width  $\leq$  300µs; duty cycle  $\leq$  2%.

For design aid only, not subject to production testing.
Switching characteristics are independent of operating junction temperatures.



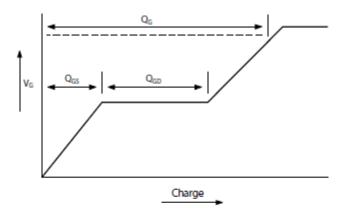




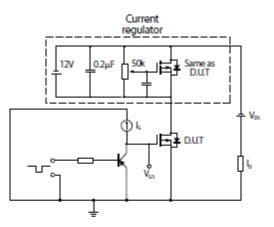




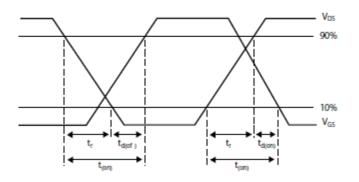
## **Test Circuits**



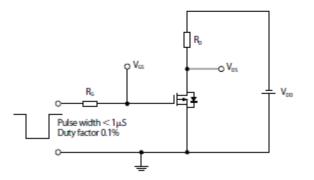




Gate charge test circuit



Switching time waveforms

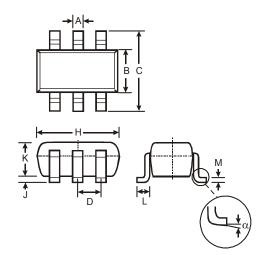


Switching time test circuit



# **Package Outline Dimensions**

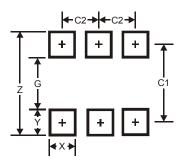
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT26					
Dim	Min	Max	Тур		
Α	0.35	0.50	0.38		
В	1.50	1.70	1.60		
С	2.70	3.00	2.80		
D			0.95		
н	2.90	3.10	3.00		
J	0.013	0.10	0.05		
κ	1.00	1.30	1.10		
L	0.35	0.55	0.40		
М	0.10	0.20	0.15		
α	0°	8°			
All Dimensions in mm					

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.20
G	1.60
x	0.55
Y	0.80
C1	2.40
C2	0.95



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